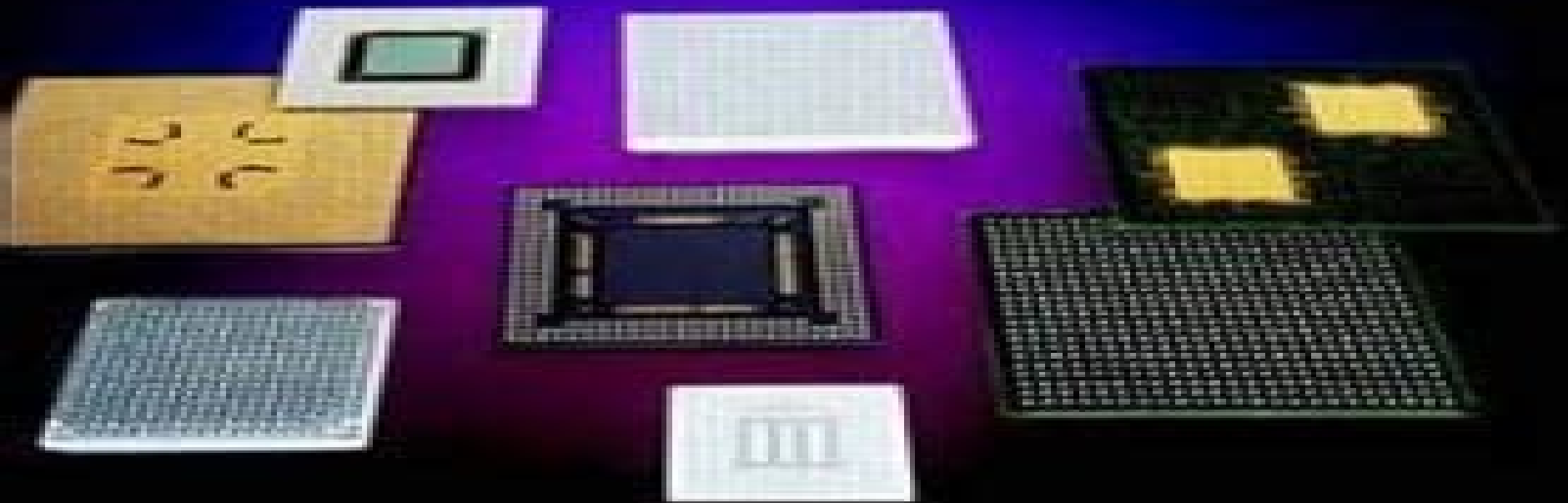


JENNIE S. HWANG, Ph.D.



Modern Solder Technology for Competitive Electronics Manufacturing

Modern Solder Technology For Competitive Electronics Manufacturing

BM King

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Modern Solder Technology for Competitive Electronics Manufacturing Jennie S. Hwang, 1996 Introduction Advanced Surface Mount Technology and Die Attach Techniques Solder Material Soldering Chemistry Solderability Microstructure of Solders Aqueous Cleaning Manufacture No Clean Manufacture Protective and Reactive Atmosphere Soldering Surface Mount Fine Pitch Technology Surface Mount BGA PAC Technology Soldering Methodology and Equipment Soldering and Soldering Related Issues Strengthened Solders Lead Free Solders Solder Joint Failure Mode Solder Joint Failure Assessment Case Studies Solder Joint Quality and Reliability New and Emerging Specifications and Standards Future Trends

Electronics Manufacturing John H. Lau, C. P. Wong, Ning-Cheng Lee, Ricky S. W. Lee, 2002-09-13

ELECTRONICS MANUFACTURING WITH LEAD FREE HALOGEN FREE AND CONDUCTIVE ADHESIVE MATERIALS This comprehensive guide provides cutting edge information on lead free halogen free and conductive adhesive technologies and their application to low cost high density reliable and green products Essential for electronics manufacturing and packaging professionals who wish to master lead free halogen free and conductive adhesive problem solving methods and those demanding cost effective designs and high yield environmental benign manufacturing processes this valuable reference covers all aspects of this fast growing field Written for design materials process equipment manufacturing reliability component packaging and system engineers and technical and marketing managers in electronics and photonics packaging and interconnection this book teaches a practical understanding of the cost design materials process equipment manufacturing and reliability issues of lead free halogen free and conductive adhesive technologies Among the topics explored Chip wafer level interconnects with lead free solder bumps Lead free solder wafer bumping with micro ball mounting and paste printing methods Lead free solder joint reliability of WLCSPs on organic and ceramic substrates Chip wafer level interconnects with solderless bumps such as Ni Au Au and Cu Cu wires Au wires Au studs and Cu studs Design materials process and reliability of WLCSPs with solderless interconnects on PCB substrate Halogen free molding compounds for PQFP PBGA and MAP PBGA packages Environmentally benign die attach films for PQFP and PBGA packages and lead free die attach bonding techniques for IC packaging Environmental issues for conventional PCBs and substrates Some environmentally conscious flame retardants for PCBs and organic substrates Emerging technologies for fabricating environmental friendly PCBs such as design for environment green PCB manufacturing and environmental safety Lead free soldering activities such as legislation consortia programs and regional preferences on lead free solder alternatives Criteria development approaches and varieties of alloys and properties of lead free solders Physical mechanical chemical electrical and soldering properties of lead free solders Manufacturing process and performance of lead free surface finishes for both PCB and component applications Implementation and execution challenges of lead free soldering especially for the reflow and wave soldering process Fundamental understanding of electrically conductive adhesive ECA technology Effects of

lubricant removal and cure shrinkage on ECAs Mechanisms underlying the contact resistance shifts of ECAs Effects of electrolytes and moisture absorption on contact resistance shifts of ECAs Stabilization of contact resistance of ECAs using various additives

Assembly and Reliability of Lead-Free Solder Joints John H. Lau, Ning-Cheng Lee, 2020-05-29 This book focuses on the assembly and reliability of lead free solder joints Both the principles and engineering practice are addressed with more weight placed on the latter This is achieved by providing in depth studies on a number of major topics such as solder joints in conventional and advanced packaging components commonly used lead free materials soldering processes advanced specialty flux designs characterization of lead free solder joints reliability testing and data analyses design for reliability and failure analyses for lead free solder joints Uniquely the content not only addresses electronic manufacturing services EMS on the second level interconnects but also packaging assembly on the first level interconnects and the semiconductor back end on the 3D IC integration interconnects Thus the book offers an indispensable resource for the complete food chain of electronics products

Lead-free Electronics Sanka Ganesan, Michael G. Pecht, 2006-02-17 Lead free Electronics provides guidance on the design and use of lead free electronics as well as technical and legislative perspectives All the complex challenges confronting the electronics industry are skillfully addressed Complying with state legislation Implementing the transition to lead free electronics including anticipating associated costs and potential supply chain issues Understanding intellectual property issues in lead free alloys and their applications including licensing and infringement Implementing cost effective manufacturing and testing Reducing risks due to tin whiskers Finding lead free solutions in harsh environments such as in the automotive and telecommunications industries Understanding the capabilities and limitations of conductive adhesives in lead free interconnects Devising solutions for lead free flip chip interconnects in high performance integrated circuit products Each chapter is written by leading experts in the field and carefully edited to ensure a consistent approach Readers will find all the latest information including the most recent data on cyclic thermomechanical deformation properties of lead free SnAgCu alloys and a comparison of the properties of standard Sn Pb versus lead free alloys using the energy partitioning approach With legislative and market pressure to eliminate the use of lead in electronics manufacturing this timely publication is essential reading for all engineers and professionals in the electronics industry

Electrical Contacts Milenko Braunovic, Nikolai K. Myshkin, Valery V. Konchits, 2017-12-19 Various factors affect the performance of electrical contacts including tribological mechanical electrical and materials aspects Although these behaviors have been studied for many years they are not widely used or understood in practice Combining approaches used across the globe Electrical Contacts Fundamentals Applications and Technology integrates advances in research and development in the tribological material and analytical aspects of electrical contacts with new data on electrical current transfer at the micro and nanoscales Taking an application oriented approach the authors illustrate how material characteristics tribological behavior and loading impact the degradation of contacts formation of intermetallics and overall

reliability and performance Coverage is divided broadly into three sections with the first focused on mechanics tribology materials current and heat transfer and basic reliability issues of electrical contacts The next section explores applications such as power connections electronic connections and sliding contacts while the final section presents the diagnostic and monitoring techniques used to investigate and measure phenomena occurring at electrical contact interfaces Numerous references to current literature reflect the fact that this book is the most comprehensive survey in the field Explore an impressive collection of data theory and practical applications in Electrical Contacts Fundamentals Applications and Technology a critical tool for anyone investigating or designing electrical equipment with improved performance and reliability in mind

Area Array Packaging Handbook Ken Gilleo, 2002 Covers design packaging construction assembly and application of all three approaches to Area Array Packaging Ball Grid Array BGA Chip Scale Package CSP and Flip Chip FC Details the pros and cons of each technology with varying applications Examines packaging ramifications of high density interconnects HDI

Electronic Materials and Processes Handbook Charles A. Harper, 2003-08-07 Electronic materials are the actual semiconductors plastics metals and ceramics that make up the chips and packages from which we construct today's cell phones palmtops and PDAs The switch in applications from PCs to smaller communications devices has driven the micro miniaturization trend in electronics which in turn has created a new set of challenges in creating materials to meet their specifications This new edition the first update of the handbook since 1993 is a complete rewrite reflecting the great importance of engineering materials for thermal management and flexibility and micro miniature sizes This new handbook will be an invaluable tool to anyone working electronic packaging fabrication or assembly design

Area Array Packaging Materials Ken Gilleo, 2004 This engineering reference covers the most important assembly processes in modern electronic packaging

Electronic Assembly Fabrication Charles A. Harper, 2002-04-10 Printed circuit history and overview Development and fabrication of IC chips Packaging of IC chips Printed circuit board fabrication

Implementing Lead-Free Electronics Jennie S. Hwang, 2004-12-10 By June 2006 any company selling electronics into the European Union and China will have to convert to lead free manufacturing processes Virtually every electronics manufacturer in the world is faced with an expensive revamp of their operations This book shows them how to choose the right Lead Free processes and make the conversion as efficiently and inexpensively as possible

International Symposium on Electronic Materials and Packaging, 2000 Topics covered by this title include flip chip running solder join reliability emerging technologies solder materials delimitation polymers for packaging design and process modelling and testing material characterization and package reliability

Electronic Failure Analysis Handbook Perry L. Martin, 1999 Annotation In the Electronic Failure Analysis Handbook you'll find top to bottom coverage of this rapidly developing field encompassing breakthrough techniques and technologies for both components and systems reliability testing performance evaluation and liability avoidance

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Electronic Packaging and

Interconnection Handbook 4/E Charles A. Harper, 2005 Whether you re designing an electronic system from scratch or engineering the project from someone else s design the Handbook gives you the tools you need to get the job done faster cheaper and more reliably than ever We guarantee it From development and design to manufacturing and testing the Handbook has you covered It s the one resource to turn to first Why not put it to the test and see for yourself Microvias: For Low Cost, High Density Interconnects John H. Lau, Ricky S. W. Lee, 2001-05-21 State of the art introduction to high density interconnect technology The first ever book on this hot topic Microvias Low Cost High Density Interconnects gives you a thorough look at the technology that s changing the nature of printed circuit boards and driving the mobile electronic revolution A must for electronics and mechanical engineers John Lau and Ricky Lee s intensive introduction to microvia technology expertly covers all major techniques You get important details on mechanical NC drilling laser drilling photo defined chemical and plasma etching and conductive ink formation You also get a survey of the work of leading companies and their products including Canon Compaq Fujitsu Limited Gore Hitachi Chemical Co Ibiden IBM JCI JVC K S X Lam Kyocera JME Matsushita Mitsubishi NEC Samsung Sheldahl Shinko Toshiba **Thin Film Technology Handbook** Aicha Elshabini, Aicha Elshabini-Riad, Fred D. Barlow, 1998 The most comprehensive source available on the preparation characterization and emerging applications of thin film This book features extensive new advances applied in multichip modules MCMs and covers the basic principles and applications of thin film deposition techniques for practical use It provides and develops design guidelines to realize multilayer structures in microcircuits thus addressing a critical and rapidly growing area *Electronic Systems Quality Management Handbook* Marsha Ludwig-Becker, 1997 Annotation Quality management for electronic systems has grown far beyond the basic inspection techniques of the past New performance based quality management approaches are now used at every electronics company from huge corporations to small start ups This book goes beyond generic quality approaches to present an electronics specific program for quality management

Thermal Management Handbook: For Electronic Assemblies Jerry E. Sergeant, Al Krum, 1998 Publisher s Note Products purchased from Third Party sellers are not guaranteed by the publisher for quality authenticity or access to any online entitlements included with the product The hands on guide to thermal management In recent years heat sensitive electronic systems have been miniaturized far more than their heat producing power supplies leading to major design and reliability challenges and making thermal management a critical design factor This timely handbook covers all the practical issues that any packaging engineer must consider with regard to the thermal management of printed circuit boards hybrid circuits and multichip modules Readers will also benefit from the extensive data on material properties and circuit functions thus enabling more intelligent decisions at the design stage and preventing thermal related problems from occurring in the first place **The International Journal of Microcircuits and Electronic Packaging**, 2001 *Proceedings of the ... International Symposium on Microelectronics*, 2000 Electronic Connector Handbook Robert S. Mroczkowski, 1998

Includes data on connectors this handbook covers the basic functions of connectors and details the range of electronic connectors It discusses connector parameters in an application context to expedite implementation and provides design and materials selection criteria for the range of connectors

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